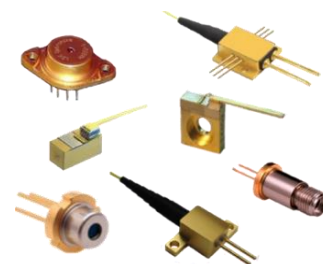


- ⊗ Wavelength: 808+/-3 nm
- ⊗ Output Power: Up to 2000mW free space / 1600mW fiber coupled
- ⊗ High output power and high efficiency
- ⊗ Proven reliability
- ⊗ Custom packaging available
- ⊗ Custom wavelengths and laser designs are available.



The LDX-3210-808 is a high-power laser diode chip. Designed for low divergence and high brightness, and offers proven reliability. This chip is used in a wide range of applications in the medical, industrial, research, and military markets.

These lasers are available in the following free space and fiber-coupled packages:

C-mount, B-mount, COS, 9mm, 9mm Isolated, TO3, TO3-TEC, HHL, 9mm SMA, FCP (2 Pin), HHLFC, and custom package options.

Device Specifications (Specified values are at rated power at 25° on a C-mount)

Parameter	LDX-3210-808	Units
Output Power	2,000	mW
Wavelength	808	+/-3 nm
Spectral Width	1.9	nm
Operating Temperature	25	°C
Aperture Size	100	um
Operating Current	2,010	mA
Threshold Current	285	mA
Slope Efficiency	1.15	W/A
Forward Voltage	2.1	V
Fast Axis Divergence	36	° (FWHM)
Slow Axis Divergence	7	° (FWHM)
Polarization	TE	N/A
Fiber Size HHL, BTF, FCP ¹	105 or 200	um
Min. Fiber Size 9mm SMA ²	250	um
Expected Lifetime ³	>10,000	Hours (EOL) ⁴

Unless otherwise indicated, all values are nominal.

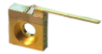
1. Other fiber diameters are available upon requested.
2. If minimum fiber size is used, a high power SMA connector is required.
3. Lifetime is greatly affected by Package type, Operating temperature, Thermal resistance, Operation (CW vs Off/On), and Packaging stress
4. End of Life (EOL) is defined as when the operating current must be increased by >20% to maintain the Beginning of Life (BOL) optical output power.

LDX follows a policy of continuous product improvement.
Specifications are subject to change without notice.

These components do not comply with the Federal Regulations (21 CFR Subchapter 1) as administered by the Center for Devices and Radiological health. Purchaser acknowledges that his/her products must comply with these regulations before they can be sold to a customer



Free Space Package - Exposed Emitter

Package		Features	Options	Drawing
C-Mount Package		Small footprint with screw mounting Material – Copper (OFHC) Fast-axis lensing	Fast-axis lensing	
B-Mount Package		Very small footprint Requires soldering to heatsink Material – Copper Tungsten (CuW)	Fast-axis lensing	
Chip-on-Submount		Very small footprint Requires soldering to heatsink Material – BeO	Fast-axis lensing	

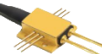
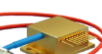
Free Space Package - Hermetically Sealed Windowed Packages

Package		Features	Options	Drawing
9mm Package		Industry-standard package Header material – Copper	Photodiode, Isolated package, Fast-axis lensing	
TO-3 Package		Mounting to heatsink with screws Header material – Copper	TEC, Thermistor, Photodiode, Fast-axis lensing	
HHL Package		Internal peltier cooler (TEC), thermistor, and photodiode Header material – Copper	Fast-axis lensing	

FAC Lensing Options:

Best Collimation	L1	Less than 1° divergence in the fast axis direction.
Squared Beam FAC	L2	Matches the fast-axis to the slow-axis divergence.

Fiber Coupled Packages - Hermetically Sealed - >80% Coupling Efficiency

Package		Features	Options	Drawing
9mm SMA FC Package		Industry-standard package SMA connector for detachable fiber Header material – Copper	Photodiode, Isolated package	
8-Pin BFC Package		Built-in internal TEC and Photodiode Fiber pigtail with SMA connector Header material – Copper	Thermistor	
2-Pin FCP Package		Fiber pigtail with SMA connector Header material – Copper	none	
HHL-FC Package		Fiber pigtail with SMA connector Internal peltier cooler (TEC), thermistor, and photodiode Header material – Copper	none	

Part Numbering System

LDX-XXXX-XXX-XXX-XXX LDX Optronics Chip Design Wavelength Package Type C – C-Mount B – B-Mount Q – Q-Mount COS – Chip on Submount 9 – 9mm Package TO3 – TO-3 Package HHL – HHL Package 9-SMA – 9mm SMA Package HHL-FC – HHL Package BFC – 8 pin High Heat Load FCP – 2-pin Package CHIP – Unmounted Chip BAR – Unmounted Bar Options TEC – Internal TEC PD – Photodiode T – Thermistor L1 – FAC Lens, Best Collimation L2 – FAC Lens, Squared Beam AR – Low AR Coating		Part Number	Description
		LDX-3115-680-9	Semiconductor Laser Diode, 680±3 nm, 1200mW, 150um emitter, 9mm Package
		LDX-2405-690-BFC-105	Semiconductor Laser Diode, 690±3 nm, 400mW, 50um emitter, Pigtailed Fiber Coupled 8-pin BFC Package w/ >80% Output Power from Fiber, Includes 105um, 0.22NA, 1m long fiber pigtail with SMA connector
		LDX-2410-645-B-L1	Semiconductor Laser Diode, 645±5 nm, 400mW, 100um emitter, B-mount w/ FAC Lensing, Best Collimation
		LDX-2710-660-HHL-L2	Semiconductor Laser Diode, 660±3 nm, 750mW, 100um emitter, HHL Package w/ TEC, PD, Thermistor, FAC Lens, Squared Beam

For all handling and mounting precautions, see the [LDX Catalog](#)